Preferred Device

# **Silicon Controlled Rectifiers**

# **Reverse Blocking Thyristors**

Designed primarily for half-wave ac control applications, such as motor controls, heating controls and power supplies.

- Glass Passivated Junctions with Center Gate Geometry for Greater Parameter Uniformity and Stability
- Small, Rugged, Thermowatt Construction for Low Thermal Resistance, High Heat Dissipation and Durability
- Blocking Voltage to 800 Volts
- Device Marking: Logo, Device Type, e.g., 2N6394, Date Code

#### \*MAXIMUM RATINGS (T<sub>J</sub> = 25°C unless otherwise noted)

Rating	Symbol	Value	Unit	
Peak Repetitive Off–State Voltage <sup>(1)</sup> (T <sub>J</sub> = -40 to 125°C, Sine Wave, 50 to 60 Hz, Gate Open)  2N6394 2N6395 2N6397 2N6399	VDRM, VRRM	50 100 400 800	Volts	
On-State RMS Current (180° Conduction Angles; T <sub>C</sub> = 90°C)	IT(RMS)	12	А	
Peak Non-Repetitive Surge Current (1/2 Cycle, Sine Wave, 60 Hz, T <sub>J</sub> = 125°C)	ITSM	100	A	
Circuit Fusing (t = 8.3 ms)	l <sup>2</sup> t	40	A <sup>2</sup> s	
Forward Peak Gate Power (Pulse Width ≤ 1.0 μs, T <sub>C</sub> = 90°C)	РGМ	20	Watts	
Forward Average Gate Power (t = 8.3 ms, T <sub>C</sub> = 90°C)	PG(AV)	0.5	Watts	
Forward Peak Gate Current (Pulse Width ≤ 1.0 μs, T <sub>C</sub> = 90°C)	I <sub>GM</sub>	2.0	А	
Operating Junction Temperature Range	TJ	-40 to +125	°C	
Storage Temperature Range	T <sub>stg</sub>	-40 to +150	°C	

<sup>\*</sup>Indicates JEDEC Registered Data

(1) VDRM and VRRM for all types can be applied on a continuous basis. Ratings apply for zero or negative gate voltage; however, positive gate voltage shall not be applied concurrent with negative potential on the anode. Blocking voltages shall not be tested with a constant current source such that the voltage ratings of the devices are exceeded.

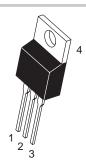


#### ON Semiconductor

http://onsemi.com

# SCRs 12 AMPERES RMS 50 thru 800 VOLTS





TO-220AB CASE 221A STYLE 3

PIN ASSIGNMENT		
1	Cathode	
2	Anode	
3	Gate	
4	Anode	

#### ORDERING INFORMATION

Device	Package	Shipping
2N6394	TO220AB	500/Box
2N6395	TO220AB	500/Box
2N6397	TO220AB	500/Box
2N6399	TO220AB	500/Box

**Preferred** devices are recommended choices for future use and best overall value.

#### THERMAL CHARACTERISTICS

Characteristic		Max	Unit
Thermal Resistance, Junction to Case	$R_{\theta JC}$	2.0	°C/W
Maximum Lead Temperature for Soldering Purposes 1/8" from Case for 10 Seconds	TL	260	°C

#### **ELECTRICAL CHARACTERISTICS** (T<sub>C</sub> = 25°C unless otherwise noted.)

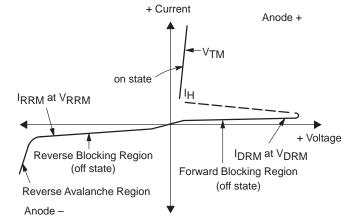
Characteristic	Symbol	Min	Тур	Max	Unit
OFF CHARACTERISTICS	•	•			•
*Peak Repetitive Forward or Reverse Blocking Current ( $V_{AK}$ = Rated $V_{DRM}$ or $V_{RRM}$ , Gate Open) $T_J = 25^{\circ}C$ $T_J = 125^{\circ}C$	IDRM, IRRM	_	_	10 2.0	μA mA
ON CHARACTERISTICS					
*Peak Forward On-State Voltage(1) (I <sub>TM</sub> = 24 A Peak)	V <sub>TM</sub>	_	1.7	2.2	Volts
*Gate Trigger Current (Continuous dc) (V <sub>D</sub> = 12 Vdc, R <sub>L</sub> = 100 Ohms)	<sup>I</sup> GT	_	5.0	30	mA
*Gate Trigger Voltage (Continuous dc) (V <sub>D</sub> = 12 Vdc, R <sub>L</sub> = 100 Ohms)	VGT	_	0.7	1.5	Volts
Gate Non-Trigger Voltage (V <sub>D</sub> = 12 Vdc, R <sub>L</sub> = 100 Ohms, T <sub>J</sub> = 125°C)	V <sub>GD</sub>	0.2	_	_	Volts
*Holding Current (V <sub>D</sub> = 12 Vdc, Initiating Current = 200 mA, Gate Open)	lн		6.0	50	mA
Turn-On Time $(I_{TM} = 12 \text{ A, } I_{GT} = 40 \text{ mAdc, } V_D = \text{Rated } V_{DRM})$	tgt	_	1.0	2.0	μs
Turn-Off Time ( $V_D$ = Rated $V_{DRM}$ ) ( $I_{TM}$ = 12 A, $I_R$ = 12 A) ( $I_{TM}$ = 12 A, $I_R$ = 12 A, $I_J$ = 125°C)	tq		15 35		μs
DYNAMIC CHARACTERISTICS					
Critical Rate-of-Rise of Off-State Voltage Exponential (V <sub>D</sub> = Rated V <sub>DRM</sub> , T <sub>J</sub> = 125°C)	dv/dt	_	50	_	V/μs

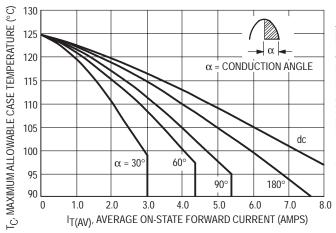
<sup>\*</sup>Indicates JEDEC Registered Data

<sup>(1)</sup> Pulse Test: Pulse Width  $\leq 300~\mu sec,~Duty~Cycle \leq 2\%.$ 

# **Voltage Current Characteristic of SCR**

Symbol	Parameter
V <sub>DRM</sub>	Peak Repetitive Off State Forward Voltage
IDRM	Peak Forward Blocking Current
VRRM	Peak Repetitive Off State Reverse Voltage
IRRM	Peak Reverse Blocking Current
V <sub>TM</sub>	Peak On State Voltage
I⊔	Holding Current

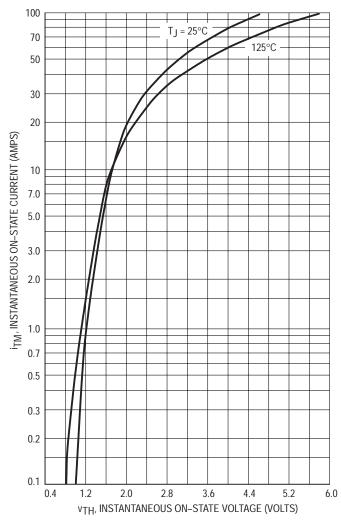




20 P(AV), AVERAGE POWER (WATTS) 18 16 180°  $\alpha$  = CONDUCTION ANGLE 14 90° 12  $\alpha = 30^{\circ}$ 10 8.0 6.0 4.0  $T_J \approx 125^{\circ}C$ 2.0 3.0 4.0 5.0 6.0 7.0  $I_{T(AV)}$ , AVERAGE ON-STATE CURRENT (AMPS)

Figure 1. Current Derating

Figure 2. Maximum On-State Power Dissipation



100 1 CYCLE → 95 ITSM, PEAK SURGE CURRENT (AMP) 90 85 80 75 70 T<sub>J</sub> = 125°C 65 f = 60 Hz 60 SURGE IS PRECEDED AND 55 FOLLOWED BY RATED CURRENT 50 1.0 2.0 6.0 8.0 10 NUMBER OF CYCLES

Figure 3. On-State Characteristics

Figure 4. Maximum Non-Repetitive Surge Current

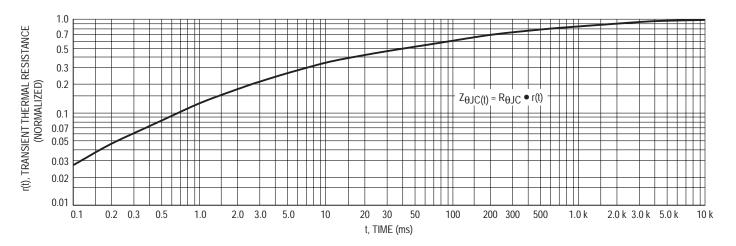
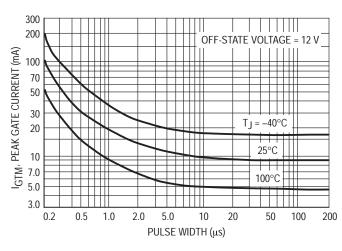


Figure 5. Thermal Response

#### TYPICAL CHARACTERISTICS

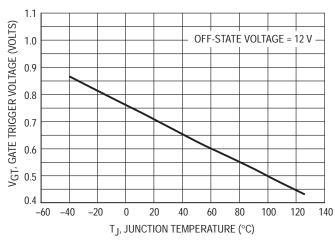


3.0 OFF-STATE VOLTAGE = 12 V

OFF-STATE VOLT

Figure 6. Typical Gate Trigger Current versus Pulse Width

Figure 7. Typical Gate Trigger Current versus Temperature



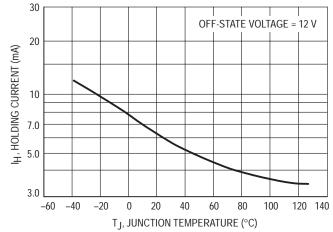
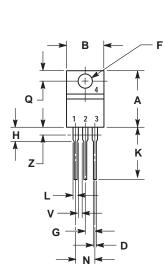


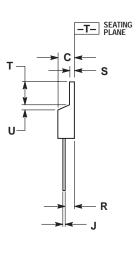
Figure 8. Typical Gate Trigger Voltage versus Temperature

Figure 9. Typical Holding Current versus Temperature

#### **PACKAGE DIMENSIONS**

#### TO-220AB CASE 221A-07 ISSUE Z





- NOTES:
  1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: INCH.
  3. DIMENSION Z DEFINES A ZONE WHERE ALL BODY AND LEAD IRREGULARITIES ARE ALLOWED.

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
Α	0.570	0.620	14.48	15.75
В	0.380	0.405	9.66	10.28
С	0.160	0.190	4.07	4.82
D	0.025	0.035	0.64	0.88
F	0.142	0.147	3.61	3.73
G	0.095	0.105	2.42	2.66
Н	0.110	0.155	2.80	3.93
J	0.014	0.022	0.36	0.55
K	0.500	0.562	12.70	14.27
L	0.045	0.060	1.15	1.52
N	0.190	0.210	4.83	5.33
Q	0.100	0.120	2.54	3.04
R	0.080	0.110	2.04	2.79
S	0.045	0.055	1.15	1.39
T	0.235	0.255	5.97	6.47
U	0.000	0.050	0.00	1.27
V	0.045		1.15	
Z		0.080		2.04

STYLE 3:
PIN 1. CATHODE
2. ANODE
3. GATE
4. ANODE

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